

# MBRF30H150CTG, MBR30H150CTG

## SWITCHMODE™ Power Rectifier 150 V, 30 A

### Features and Benefits

- Low Forward Voltage
- Low Power Loss/High Efficiency
- High Surge Capability
- 30 A Total (15 A Per Diode Leg)
- Guard-Ring for Stress Protection
- These are Pb-Free Devices

### Applications

- Power Supply – Output Rectification
- Power Management
- Instrumentation

### Mechanical Characteristics:

- Case: Epoxy, Molded
- Epoxy Meets UL 94 V-0 @ 0.125 in
- Weight (Approximately): 1.9 Grams (TO-220 & TO-220FP)
- Finish: All External Surfaces Corrosion Resistant and Terminal Leads are Readily Solderable
- Lead Temperature for Soldering Purposes:  
260°C Max. for 10 Seconds

### MAXIMUM RATINGS

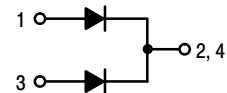
Please See the Table on the Following Page



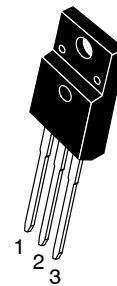
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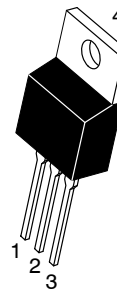
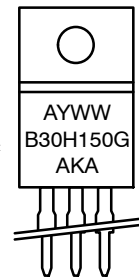
## SCHOTTKY BARRIER RECTIFIER 30 AMPERES, 150 VOLTS



### MARKING DIAGRAMS



TO-220 FULLPAK™  
CASE 221D  
STYLE 3



TO-220AB  
CASE 221A  
STYLE 6



A = Assembly Location  
Y = Year  
WW = Work Week  
B30H150 = Device Code  
G = Pb-Free Device  
AKA = Polarity Designator

### ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 2 of this data sheet.

# MBRF30H150CTG, MBR30H150CTG

## MAXIMUM RATINGS (Per Diode Leg)

Rating	Symbol	Value	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	$V_{RRM}$ $V_{RWM}$ $V_R$	150	V
Average Rectified Forward Current (Per Leg) (Rated $V_R$ ) $T_C = 124^\circ\text{C}$ (Per Device)	$I_{F(AV)}$	15 30	A
Nonrepetitive Peak Surge Current (Surge applied at rated load conditions halfwave, single phase, 60 Hz)	$I_{FSM}$	200	A
Operating Junction Temperature (Note 1)	$T_J$	-20 to +150	$^\circ\text{C}$
Storage Temperature	$T_{stg}$	-65 to +150	$^\circ\text{C}$
Voltage Rate of Change (Rated $V_R$ )	dv/dt	10,000	V/ $\mu\text{s}$
ESD Ratings: Machine Model = C Human Body Model = 3B		> 400 > 8000	V

## THERMAL CHARACTERISTICS

Rating	Symbol	Value	Unit
Maximum Thermal Resistance (MBR30H150CTG) - Junction-to-Case (MBRF30H150CTG) - Junction-to-Ambient - Junction-to-Case	$R_{\theta JC}$ $R_{\theta JA}$ $R_{\theta JC}$	2.0 45 2.5	$^\circ\text{C}/\text{W}$

## ELECTRICAL CHARACTERISTICS (Per Diode Leg)

Rating	Symbol	Typ	Max	Unit
Maximum Instantaneous Forward Voltage (Note 2) ( $I_F = 5\text{ A}$ , $T_C = 25^\circ\text{C}$ ) ( $I_F = 5\text{ A}$ , $T_C = 125^\circ\text{C}$ ) ( $I_F = 15\text{ A}$ , $T_C = 25^\circ\text{C}$ ) ( $I_F = 15\text{ A}$ , $T_C = 125^\circ\text{C}$ )	$V_F$	0.69 0.55 0.98 0.68	0.75 0.60 1.11 0.73	V
Maximum Instantaneous Reverse Current (Note 2) (Rated DC Voltage, $T_C = 25^\circ\text{C}$ ) (Rated DC Voltage, $T_C = 125^\circ\text{C}$ )	$i_R$		60 50	$\mu\text{A}$ mA

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

- The heat generated must be less than the thermal conductivity from Junction-to-Ambient:  $dP_D/dT_J < 1/R_{\theta JA}$ .
- Pulse Test: Pulse Width = 300  $\mu\text{s}$ , Duty Cycle  $\leq 2.0\%$ .

## DEVICE ORDERING INFORMATION

Device Order Number	Package Type	Shipping <sup>†</sup>
MBRF30H150CTG	TO-220FP (Pb-Free)	50 Units / Rail
MBR30H150CTG	TO-220 (Pb-Free)	50 Units / Rail

<sup>†</sup>For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification Brochure, BRD8011/D.

# MBRF30H150CTG, MBR30H150CTG

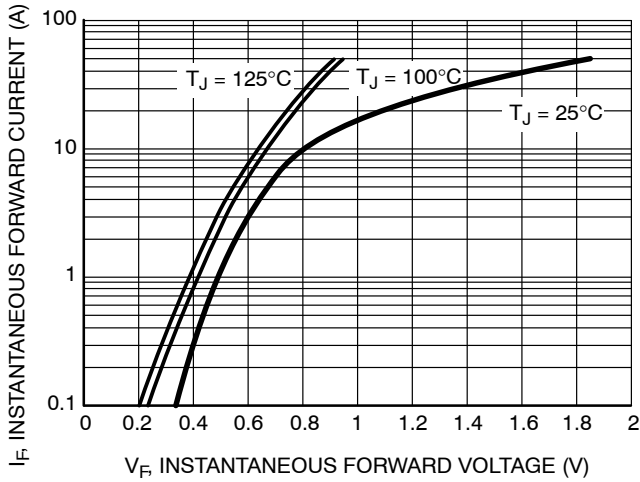


Figure 1. Typical Forward Voltage

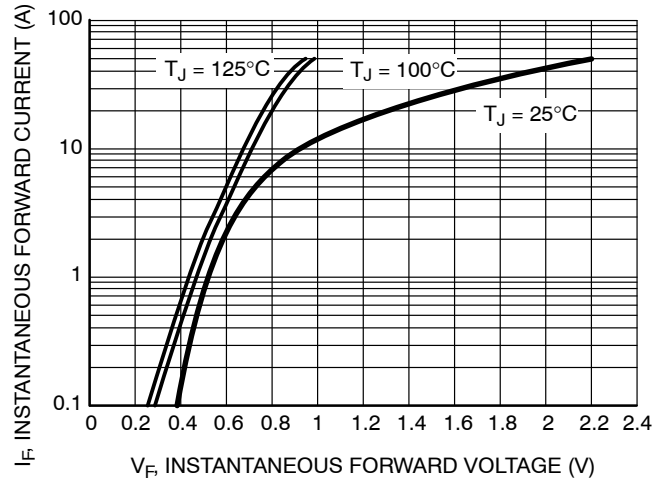


Figure 2. Maximum Forward Voltage

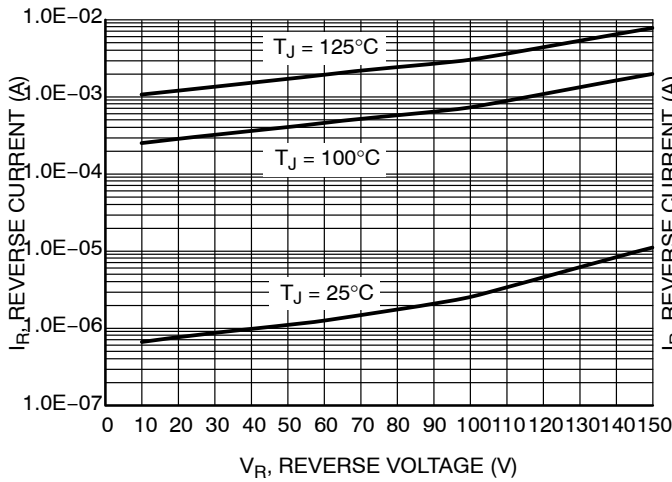


Figure 3. Typical Reverse Current

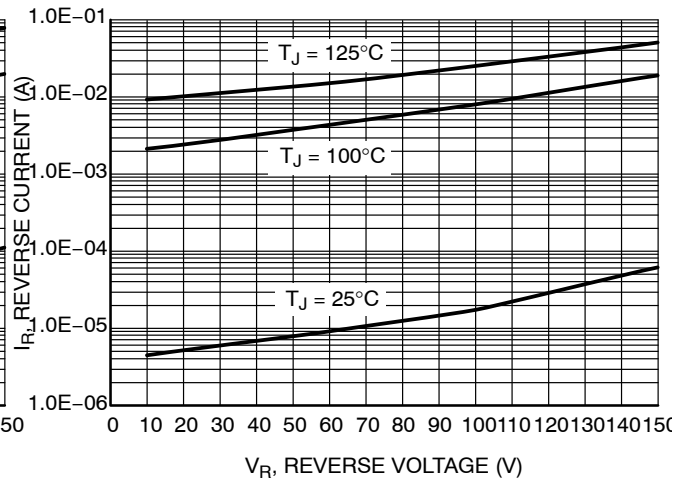


Figure 4. Maximum Reverse Current

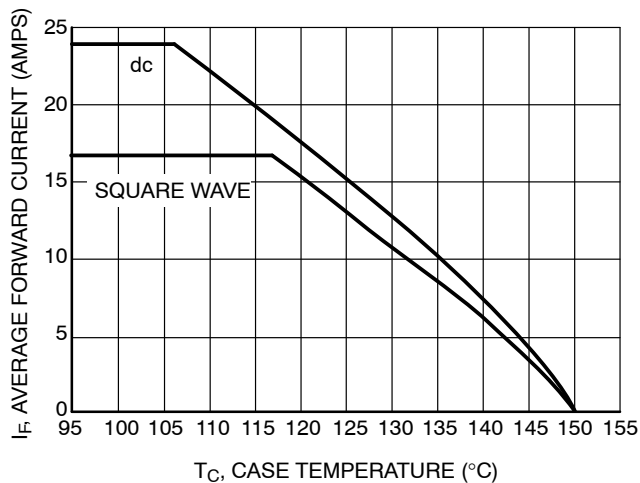


Figure 5. Current Derating

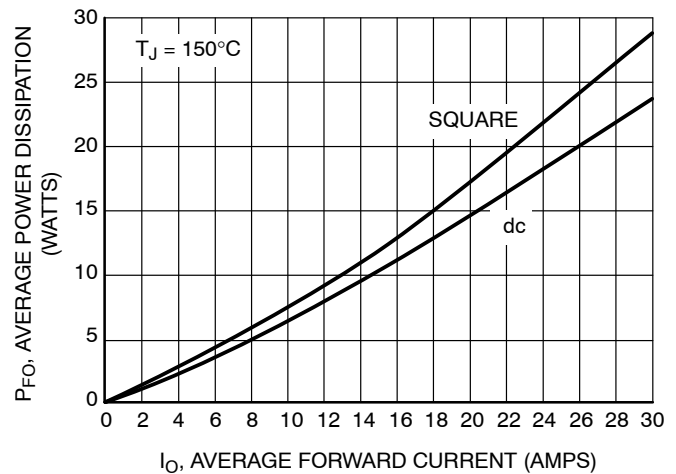


Figure 6. Forward Power Dissipation

# MBRF30H150CTG, MBR30H150CTG

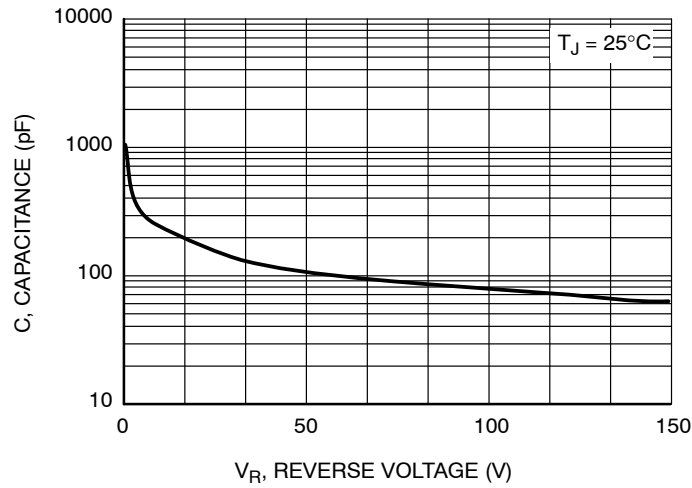


Figure 7. Capacitance

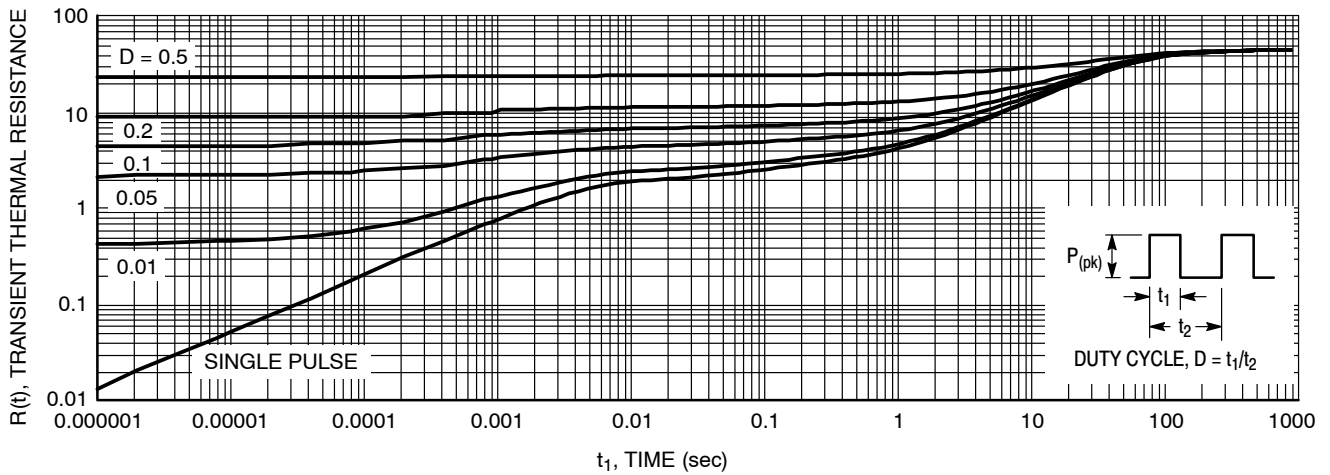


Figure 8. Thermal Response Junction-to-Ambient for MBR30H150CTG

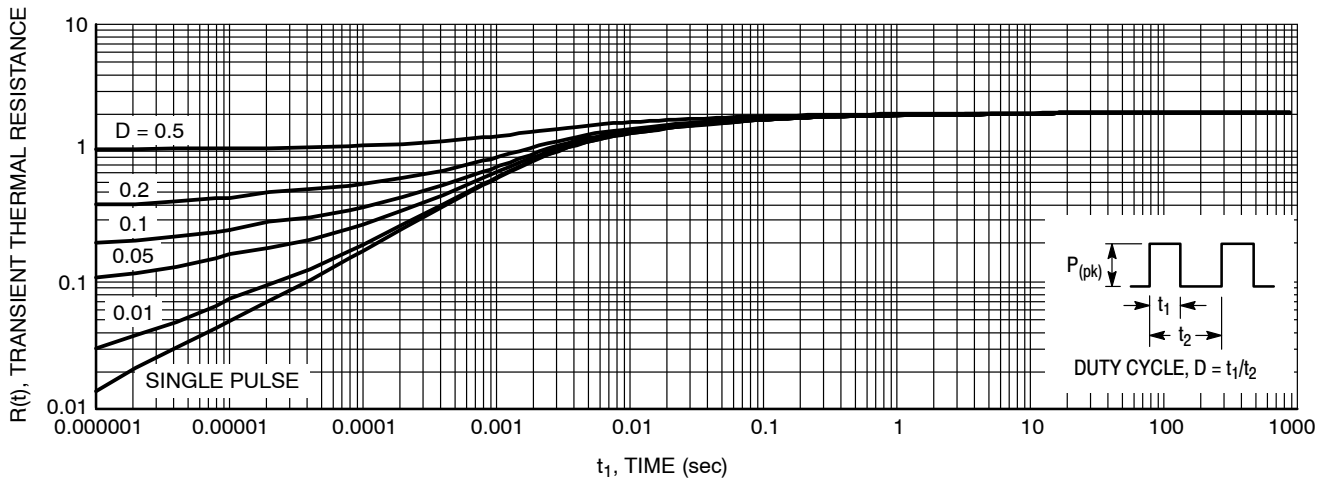


Figure 9. Thermal Response Junction-to-Case for MBR30H150CTG

# MBRF30H150CTG, MBR30H150CTG

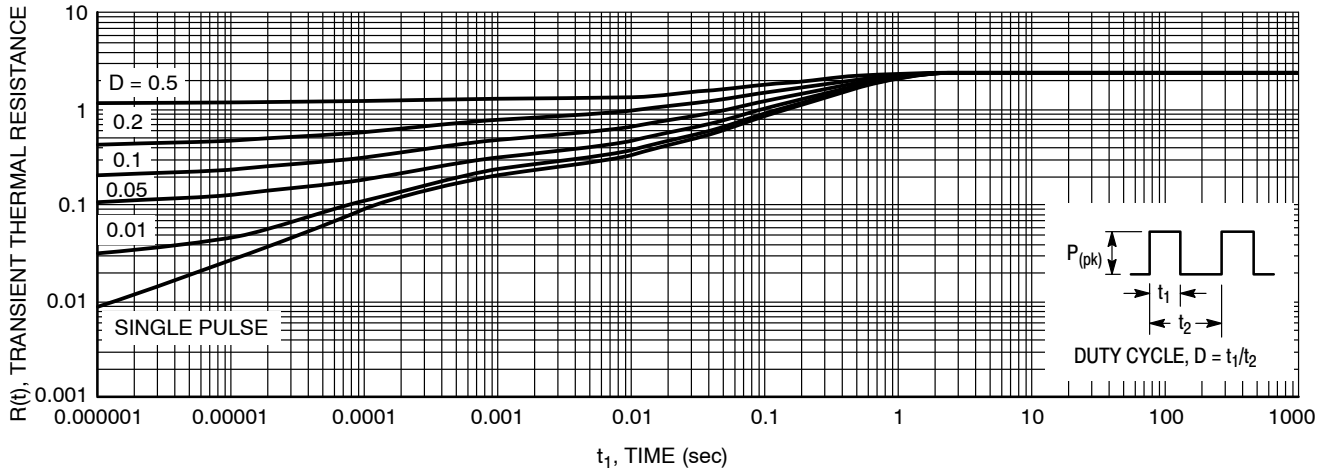
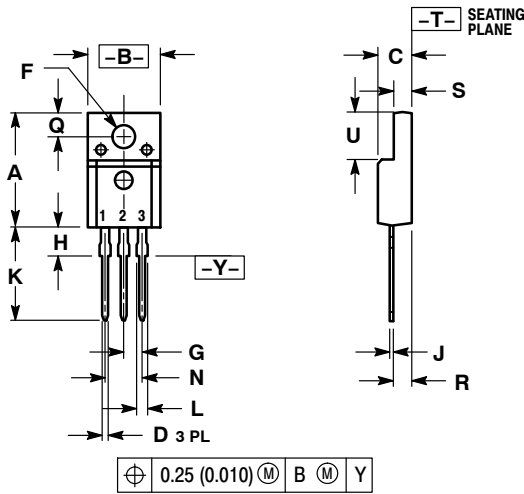


Figure 10. Thermal Response Junction-to-Case for MBRF30H150CTG

# MBRF30H150CTG, MBR30H150CTG

## PACKAGE DIMENSIONS

### TO-220 FULLPAK CASE 221D-03 ISSUE K



NOTES:

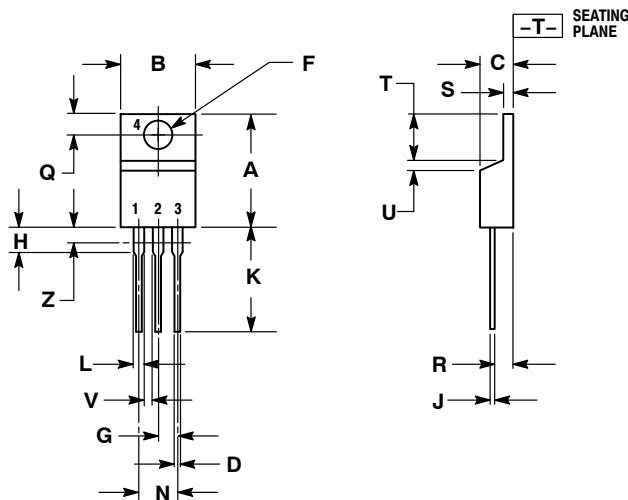
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: INCH
3. 221D-01 THRU 221D-02 OBSOLETE, NEW STANDARD 221D-03.

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.617	0.635	15.67	16.12
B	0.392	0.419	9.96	10.63
C	0.177	0.193	4.50	4.90
D	0.024	0.039	0.60	1.00
F	0.116	0.129	2.95	3.28
G	0.100 BSC		2.54 BSC	
H	0.118	0.135	3.00	3.43
J	0.018	0.025	0.45	0.63
K	0.503	0.541	12.78	13.73
L	0.048	0.058	1.23	1.47
N	0.200 BSC		5.08 BSC	
Q	0.122	0.138	3.10	3.50
R	0.099	0.117	2.51	2.96
S	0.092	0.113	2.34	2.87
U	0.239	0.271	6.06	6.88

STYLE 3:

- PIN 1. ANODE  
2. CATHODE  
3. ANODE

### TO-220 CASE 221A-09 ISSUE AF



NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: INCH.
3. DIMENSION Z DEFINES A ZONE WHERE ALL BODY AND LEAD IRREGULARITIES ARE ALLOWED.

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.570	0.620	14.48	15.75
B	0.380	0.405	9.66	10.28
C	0.160	0.190	4.07	4.82
D	0.025	0.035	0.64	0.88
F	0.142	0.161	3.61	4.09
G	0.095	0.105	2.42	2.66
H	0.110	0.155	2.80	3.93
J	0.014	0.025	0.36	0.64
K	0.500	0.562	12.70	14.27
L	0.045	0.060	1.15	1.52
N	0.190	0.210	4.83	5.33
Q	0.100	0.120	2.54	3.04
R	0.080	0.110	2.04	2.79
S	0.045	0.055	1.15	1.39
T	0.235	0.255	5.97	6.47
U	0.000	0.050	0.00	1.27
V	0.045	---	1.15	---
Z	---	0.080	---	2.04

STYLE 6:

- PIN 1. ANODE  
2. CATHODE  
3. ANODE  
4. CATHODE

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